

APPARATUS AND METHOD FOR COOLING A SEMICONDUCTOR DEVICE**ABSTRACT**

5 An apparatus and method for cooling a semiconductor device. The apparatus
comprises a chamber configured for receiving a cooling fluid; and a plurality of
contact elements comprising respective first ends disposed within the chamber;
wherein, during operation, respective second ends of contact elements contact a
silicon substrate of the semiconductor device for transferring heat generated in the
10 semiconductor device to the cooling fluid.

FIG. 1(b)